



## TC-TAP-2 Series

Shin-Etsu Silicones of America, Inc.  
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### Product Features

- High thermal conductivity
- 0.11mm thickness available
- Excellent electrical properties
- Superior strength and hardness
- UL 94 V-0 flame rated

### Typical Applications

- Vehicle inverters/converters
- Power Transistors
- Power Modules
- LED Modules

### Typical Properties

Type	High Hardness Thermal Pads
UL	Y
Low Molecular Weight Siloxane Stripped?	Y
Density @ 23C (g/cm <sup>3</sup> )	1.90
Shore A Hardness	90
Tensile Strength (MPa)	37.00
Dielectric Strength (kV/mm)	91.0
Thermal Conductivity (W/m·K)	1.80
Thermal Resistance (mm <sup>2</sup> ·K/W)	190
Usable Temp. Range (C)	-40 to +180
Thickness (mm)	0.11
Reinforced Layer	Polyimide
Sheet Size (mm)	320 x 1000 or 320 x 50m

*Note: Values are not for specification purposes.*

*Physical properties are typical for the thickness given. Other thicknesses may have slightly varying properties and are available upon request.*

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